



100% Material Declaration Data Sheet FF1738

PK215 (v1.0) January 17, 2007

Material Declaration Data Sheet

Average Weight: 16.2810 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.004160	0.026%
	Silicon	7440-21-3	100.00		0.004160	
Solder Bump					0.032250	0.198%
	Tin	7440-31-5	63.00		0.020318	
	Lead	7439-92-1	37.00		0.011933	
Underfill					0.100000	0.626%
	Silica	60676-86-0	54.50		0.054500	
	Epoxy Resin A	25068-38-6	2.50		0.002500	
	Epoxy Resin B	9003-36-5	25.00		0.025000	
	Phenolic Resin	9003-35-4	15.0		0.015000	
	Carbon Black	1333-86-4	0.50		0.000500	
	Additive	2530-83-8	2.50		0.002500	
Heat Spreader					7.350000	45.145%
	Copper	7440-50-8	99.60		7.320600	
	Nickel	7440-02-0	0.40		0.029400	
Heat Sink Adhesive					0.260000	1.597%
	Organopolysiloxane mixture	N/A	10.00		0.260000	
Substrate					6.884300	42.284%
	Copper	7440-50-8	46.49	Metal Layer	3.200511	
	Nickel	7440-02-0	0.52	Metal Layer	0.035798	
	Gold	7440-57-5	0.11	Metal Layer	0.007573	
	Glass fiber	N/A	10.40		0.715967	
	Halogen fire retardant	N/A	5.32		0.366245	
	BT (CORE)	N/A	28.56		1.966156	
	Solder Mask	N/A	8.60		0.592050	
Solder Balls					1.650290	10.136%
	Tin	7440-31-5	63.00		1.039683	
	Lead	7439-92-1	37.00		0.610607	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
1/17/07	1.0	Initial release.